

Amendments to the Specification:

Please replace paragraphs [0022] and [0023] with the following amended paragraphs:

[0022] By the way, referring to FIG. 3, the head holder 130 may be provided with one pair of guide pins 131 fitted on both sides of a top part thereof to couple with coupling holes correspondingly formed in the elevating carrier 20, thereby coupling the head holder 130 to the elevating carrier 20. ~~The unexplained symbol 135 denotes a load cell.~~

[0023] In the meantime, with regard the head structures illustrated in FIGS. ~~5 and 6~~ 2A and 2B, the head 40 includes a holding part 41 fixedly fitted to a bottom of the head holder 30 for holding the semiconductor device by vacuum, a heating part 42 on top of the holding part 41 for transfer of a heat to the semiconductor device directly when the semiconductor device is mounted in the test socket 2 (see FIG. 2A), and a compliance part 43 fitted over the heating part 42 spaced therefrom for providing degrees of freedom for an alignment between the semiconductor device held by the holding part 41 and the test socket 2.

Please replace paragraph [0032] with the following amended paragraph:

[0032] There are a plurality of holes 433 for receiving ball plungers 434, compression springs 434a, retainers 434b fitted to lower ends of the compression springs 434a, and ~~ball plungers 434~~ balls 434c retained under the retainers 434b and exposed outside of the bottom surface of the upper block 431.

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Please replace paragraph [0037] with the following amended paragraph:

[0037] FIG. 8A illustrates a state in which an alignment between the head 40 and the test socket 2 is made by the compliance part 43, to mount the semiconductor device 1 in the test socket 2, wherein, when the holding part 41 in the head 40 moves down onto the test socket 2 in a state the holding part 41 holds the semiconductor device 1, the head 40 is guided to the test socket 2 to mount the semiconductor device 1 in the socket 2 as the positioning pins 2a on the test socket 2 are inserted into the positioning holes 416 in the pocket block 411 of the head 40.